

Appl. No. 10/711,794  
Amdt. dated July 12, 2006  
Reply to Office action of June 16, 2006

**Amendments to the Claims:**

**Listing of Claims:**

Claim 1 (previously presented): A package structure comprising:

- 5 a lead frame having a plurality of leads, which includes a first recession and a second recession;
- at least a semiconductor chip;
- a plurality of first solder joints respectively positioned in the first recessions for connecting the semiconductor chip to the lead frame;
- 10 at least one passive device having a plurality of outputs respectively positioned in the second recessions; and
- a plurality of second solder joints respectively positioned in the second recessions for connecting the passive device to the lead frame.

Claim 2 (cancelled)

15

Claim 3 (cancelled)

Claim 4 (previously presented): The package structure of claim 1 wherein the passive device is an electrical resistor, a capacitor, or an inductor.

20

Claim 5 (cancelled)

Claim 6 (cancelled)

25 Claim 7 (cancelled)

Claim 8 (cancelled)

Appl. No. 10/711,794  
Amdt. dated July 12, 2006  
Reply to Office action of June 16, 2006

Claim 9 (previously presented): The package structure of claim 1 wherein the second solder joints are comprised of tin or tin alloy.

5 Claim 10 (previously presented): The package structure of claim 1 wherein the lead frame comprises a die pad connected to the semiconductor chip for radiating the heat produced by the semiconductor chip by serving as a heat sink.

10 Claim 11 (previously presented): The package structure of claim 10 wherein the die pad comprises a ground pad connected to both ground and the semiconductor chip.

Claim 12 (previously presented): The package structure of claim 1 wherein the first solder joints are comprised of tin or tin alloy.

15 Claim 13 (cancelled)

Claim 14 (cancelled)

Claim 15 (cancelled)

20 Claim 16 (cancelled)